

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:
  - a semiconductor chip;
  - 5 a mold resin sealing the semiconductor chip; and
  - a plurality of conductor leads extending from an inside of the mold resin to an outside thereof, each having a portion arranged inside the mold resin defining an internal terminal portion and a portion arranged outside the mold resin defining an external terminal portion, and an electrode of the
  - 10 semiconductor chip and the internal terminal portion of the conductor lead being connected;
  - wherein the internal terminal portion of at least one of the conductor leads forms an inductance element portion, at least a part of which is narrower than the external terminal portion.
- 15 2. The semiconductor device according to claim 1, wherein the inductance element portion has a meandering planar shape.
3. The semiconductor device according to claim 2, wherein the
- 20 conductor lead having the inductance element portion has an overlapping portion overlapping a lower surface of the semiconductor chip and is connected to the semiconductor chip in the overlapping portion.
4. The semiconductor device according to claim 3, wherein in the
- 25 overlapping portion of the electrode of the semiconductor chip and the conductor lead, the connection is made via an electrical conductor in a via hole formed in the semiconductor chip.
5. The semiconductor device according to claim 3, wherein the
- 30 overlapping portion of the conductor lead forms a die pad portion on which the semiconductor chip is mounted.
6. The semiconductor device according to claim 1, wherein the
- 35 conductor lead having the inductance element portion is connected to a source of a field-effect transistor or an emitter of a bipolar transistor formed in the semiconductor chip.

7. The semiconductor device according to claim 1, wherein the conductor lead having the inductance element portion is connected to a gate or a drain of a field-effect transistor or a base or a collector of a bipolar transistor formed in the semiconductor chip.

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8. The semiconductor device according to claim 1, wherein at least one of the conductor leads functions as a choke inductor or matching element.